- Fully Synchronous Operation for Counting and Programming
- Internal Carry Look-Ahead Circuitry for Fast Counting
- Carry Output for n-Bit Cascading
- Fully Independent Clock Circuit
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

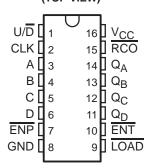
description

These synchronous 4-bit up/down binary presettable counters feature an internal carry look-ahead circuitry for cascading in high-speed counting applications. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when so instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes normally associated with asynchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock waveform.

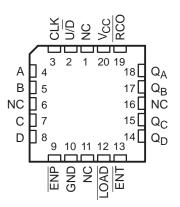
These counters are fully programmable; that is, they may be preset to either level. The load-input circuitry allows loading with the carry-enable output of cascaded counters. Because loading is synchronous, setting up a low level at the load (\overline{LOAD}) input disables the counter and causes the outputs to agree with the data inputs after the next clock pulse.

SN54ALS169B, SN54AS169A... J PACKAGE SN74ALS169B, SN74AS169A... D OR N PACKAGE (TOP VIEW)

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SN54ALS169B, SN54AS169A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

The internal carry look-ahead circuitry provides for cascading counters for n-bit synchronous application without additional gating. ENP and ENT inputs and a ripple-carry output ($\overline{\text{RCO}}$) are instrumental in accomplishing this function. Both ENP and ENT must be low to count. The direction of the count is determined by the level of the up/down (U/\overline{D}) input. When U/\overline{D} is high, the counter counts up; when low, it counts down. ENT is fed forward to enable RCO. RCO, thus enabled, produces a low-level pulse while the count is zero (all inputs low) counting down or maximum (15) counting up. This low-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed regardless of the level of the clock input. All inputs are diode clamped to minimize transmission-line effects, thereby simplifying system design.

These counters feature a fully independent clock circuit. Changes at control inputs ($\overline{\text{ENP}}$, $\overline{\text{ENT}}$, $\overline{\text{LOAD}}$, or U/D) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.

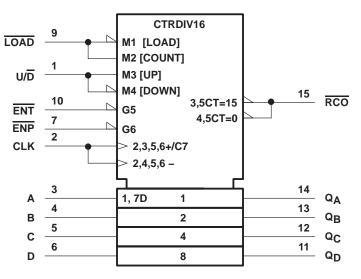
The SN54ALS169B and SN54AS169A are characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ALS169B and SN74AS169A are characterized for operation from 0°C to 70°C.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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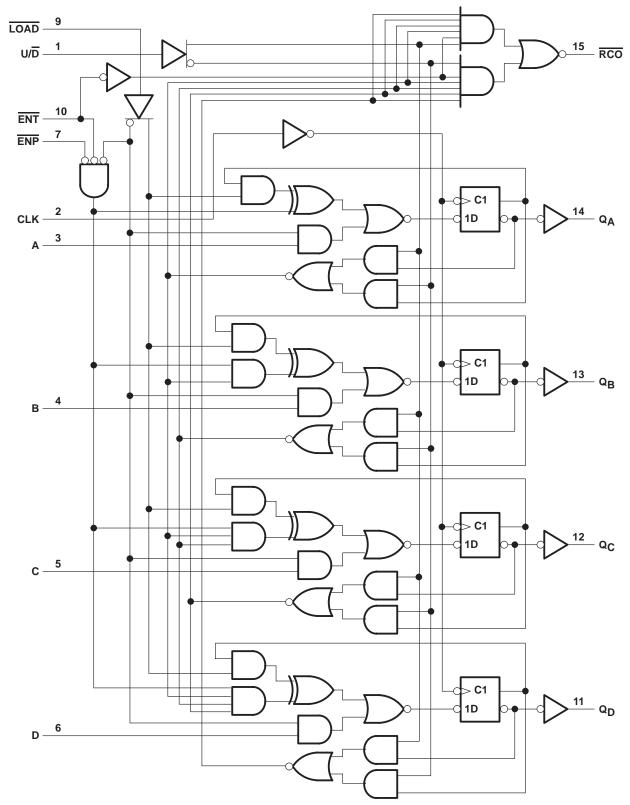
logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.



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logic diagram (positive logic)

Pin numbers shown are for the D, J, and N packages.

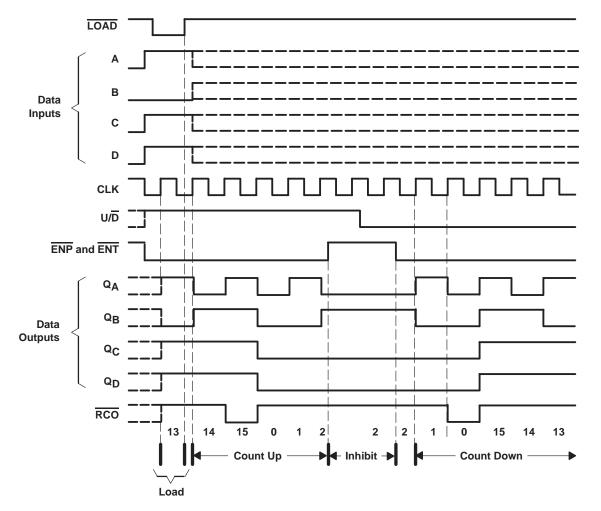


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typical load, count, and inhibit sequences

The following sequence is illustrated below:

- 1. Load (preset) to binary 13
- 2. Count up to 14, 15 (maximum), 0, 1, and 2
- 3. Inhibit
- 4. Count down to 1, 0 (minimum), 15, 14, and 13



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC}	
Input voltage, V _I	
Operating free-air temperature range, T _A : SN54ALS169B	
SN74ALS169B	0°C to 70°C
Storage temperature range	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



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recommended operating conditions

			SN	54ALS16	9B	SN7	74ALS16	9B	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			0.8	V
IОН	High-level output current				-0.4			-0.4	mA
IOL	Low-level output current				4			8	mA
fclock	Clock frequency		0		22	0		40	MHz
tw	Pulse duration, CLK high or low		14			12.5			ns
		A, B, C, or D	20			15			
		ENP or ENT	25			15			
t _{su}	Setup time before CLK↑	LOAD	20			15			ns
		U/D	28			15			
t _h	Hold time, data after CLK^\uparrow		0			0			ns
Т _А	Operating free-air temperature		-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	7507.0	TEST CONDITIONS			9B	SN7	4ALS16	9B	
PARAMETER	TEST C	ONDITIONS	MIN	түр†	MAX	MIN	TYP†	MAX	UNIT
VIK	$V_{CC} = 4.5 V,$	l _l = – 18 mA			-1.5			-1.5	V
VOH	V_{CC} = 4.5 V to 5.5 V,	I _{OH} = -0.4 mA	V _{CC} -2	2		V _{CC} -2	2		V
Max		$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	V
V _{OL}	$V_{CC} = 4.5 V$	I _{OL} = 8 mA					0.35	0.5	V
lj	$V_{CC} = 5.5 V,$	V _I = 7 V			0.1			0.1	mA
Ι _Η	$V_{CC} = 5.5 V,$	V _I = 2.7 V			20			20	μΑ
١ _{١L}	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.2			-0.2	mA
10 [‡]	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
ICC	$V_{CC} = 5.5 V$			15	25		15	25	mA

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[‡]The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.



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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	ТО (ОИТРИТ)	C _I R	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX [†]					
	(SN54AL	S169B	SN74AL	S169B			
			MIN	MAX	MIN	MAX			
fmax			22		40		MHz		
^t PLH	CLK	B00	3	20	3	20			
^t PHL	ULK	RCO	6	25	6	20	ns		
^t PLH	CLK	A	2	20	2	15			
^t PHL	ULK	Any Q	5	23	5	20	ns		
^t PLH	ENT	B00	2	16	2	13			
^t PHL	ENI	RCO	3	24	3	16	ns		
^t PLH	U/D	RCO	4	22	5	19			
^t PHL	0/0	RCO	5	26	5	19	ns		

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage, V _{CC}	
Input voltage, V _I	
Operating free-air temperature range, T _A : SN54AS169A	–55°C to 125°C
SN74AS169A	0°C to 70°C
Storage temperature range	-65°C to 150°C

Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			SN	54AS16	9A	SN	74AS169	9A	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.8			0.8	V
ЮН	High-level output current				-2			-2	mA
IOL	Low-level output current				20			20	mA
fclock*	Clock frequency		0		60	0		75	MHz
tw*	Pulse duration, CLK high or low		7.7			6.7			ns
		A, B, C, or D	10			8			
		ENP or ENT	10			8			
t _{su} *	Setup time before CLK↑	LOAD	10			8			ns
		U/D	14			11			
t _h *	Hold time, data after CLK^\uparrow		2			0			ns
ТА	Operating free-air temperature		-55		125	0		70	°C

* On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				SN	54AS16	9A	SN	74AS169	A	
	PARAMETER	TEST CON	DITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
VIK		$V_{CC} = 4.5 V,$	lj = – 18 mA			-1.2			-1.2	V
VOH		V_{CC} = 4.5 V to 5.5 V,	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2		V
VOL		$V_{CC} = 4.5 V,$	I _{OL} = 20 mA		0.25	0.5		0.25	0.5	V
	LOAD, ENT, U/D		N 7 N			0.2			0.2	
1	All others	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
	LOAD, ENT, U/D	V 55V	V 07V			40			40	•
ЧН	All others	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μA
	LOAD, ENT, U/D		N 0.4 M			-1			-1	
ΊL	All others	V _{CC} = 5.5 V,	$V_{I} = 0.4 V$			-0.5			-0.5	mA
IO‡		V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	-30		-112	mA
ICC		V _{CC} = 5.5 V			41	63		41	63	mA

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. [‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

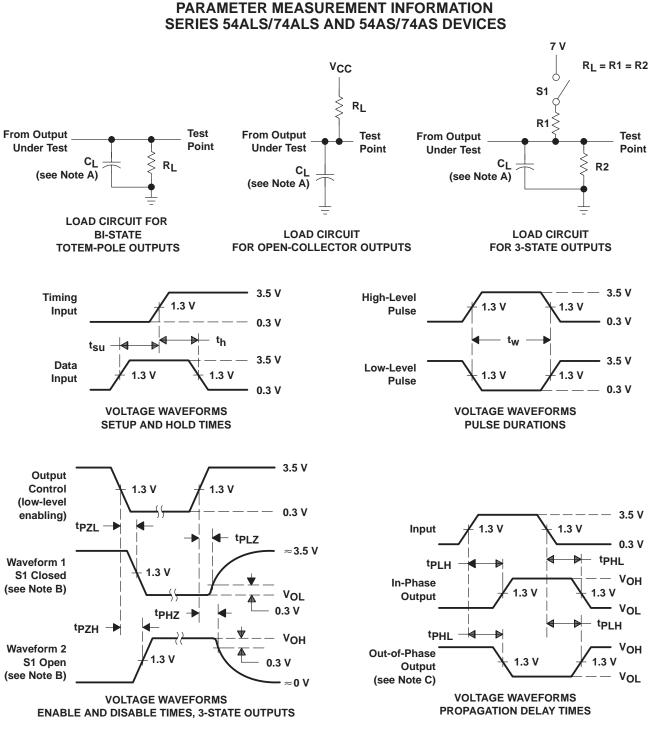
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	VC CL RL TA	UNIT			
		(,	SN54A	S169A	SN74A	S169A	
			MIN	MAX	MIN	MAX	
fmax*			60		75		MHz
^t PLH		RCO	3	17.5	3	16.5	
^t PHL	CLK	(LOAD high or low)	2	14	2	13	ns
^t PLH		A	1	7.5	1	7	
^t PHL	CLK	Any Q	2	14	2	13	ns
^t PLH			1.5	10	1.5	9	
^t PHL	ENT	RCO	1.5	10	1.5	9	ns
^t PLH	U/D	RCO	2	14	2	12	
^t PHL	0,0	KCU	2	14.5	2	13	ns

* On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested. § For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- . when measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_{f} = t_{f} = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
8302501EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8302501EA SNJ54ALS169BJ	Samples
JM38510/38003BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 38003BEA	Samples
M38510/38003BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 38003BEA	Samples
SN54ALS169BJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54ALS169BJ	Samples
SN74ALS169BD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS169B	Samples
SN74ALS169BDR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS169B	Samples
SN74ALS169BN	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS169BN	Samples
SN74ALS169BNSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS169B	Samples
SN74AS169AN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74AS169AN	Samples
SNJ54ALS169BJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8302501EA SNJ54ALS169BJ	Samples

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



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PACKAGE OPTION ADDENDUM

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS169B, SN74ALS169B :

- Catalog : SN74ALS169B
- Military : SN54ALS169B

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



Texas

STRUMENTS

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	-	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS169BDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74ALS169BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



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PACKAGE MATERIALS INFORMATION

3-Jun-2022



*All dimensions are nominal

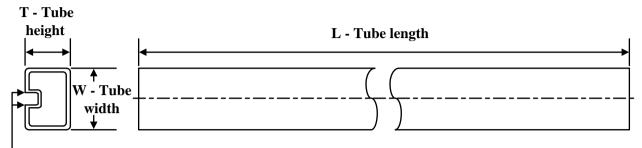
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS169BDR	SOIC	D	16	2500	340.5	336.1	32.0
SN74ALS169BNSR	SO	NS	16	2000	356.0	356.0	35.0

TEXAS INSTRUMENTS

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3-Jun-2022

TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ALS169BD	D	SOIC	16	40	507	8	3940	4.32
SN74ALS169BN	N	PDIP	16	25	506	13.97	11230	4.32
SN74ALS169BN	N	PDIP	16	25	506	13.97	11230	4.32
SN74AS169AN	N	PDIP	16	25	506	13.97	11230	4.32
SN74AS169AN	N	PDIP	16	25	506	13.97	11230	4.32

NS0016A



PACKAGE OUTLINE

SOP - 2.00 mm max height

SOP



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 2. This drawing is subject to change without notice.
 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



NS0016A

EXAMPLE BOARD LAYOUT

SOP - 2.00 mm max height

SOP



NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



NS0016A

EXAMPLE STENCIL DESIGN

SOP - 2.00 mm max height

SOP



NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

8. Board assembly site may have different recommendations for stencil design.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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